AMENDMENTS

In the Specification

None.

In the Claims

Please replace the claims with the following clean version of the entire set of pending claims, in accordance with 37 C.F.R. §1.121(c)(1)(i). Cancel all previous versions of any pending claim.

A marked up version showing amendments to any claims being changed is provided in one or more accompanying pages separate from this amendment in accordance with 37 C.F.R. §1.121(c)(1)(ii). Any claim not accompanied by a marked up version has not been changed relative to the immediate prior version, except that marked up versions are not being supplied for any added claim or canceled claim.

B1 SUB C2

9. A method of conductively interconnecting electronic components:

providing a curable adhesive composition comprising an epoxy terminated silane;

providing first and second electronic components to be conductively connected with one another;

interposing the curable adhesive composition between the first and second electronic components; and

curing the adhesive into an electrically conductive bond electrically interconnecting the first and second components.

10. The method of claim 9 wherein at least one of the components comprises a nickel containing metal surface over which the curable adhesive composition is received.

11. The method of claim 9 wherein the epoxy terminated silane comprises a glycidoxy methoxy silane.

12. The method of claim 9 wherein the epoxy terminated silane comprises a glycidoxyproplytrimethoxysilane.

13. The method of claim 9 wherein the epoxy terminated silane is present in the curable adhesive composition at less than or equal to about 2% by weight.

14. The method of claim 9 wherein the epoxy terminated silane is present in the curable adhesive composition at less than or equal to about 1% by weight.

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23. A method of conductively interconnecting electronic components comprising:

interposing a curable epoxy composition between first and second electrically conductive components to be electrically interconnected, at least one of the components comprising a metal surface with which the curable epoxy is to electrically connect; and

curing the epoxy into an electrically conductive bond electrically interconnecting the first and second components, the epoxy having an effective metal surface wetting concentration of silane to form a cured electrical interconnection having a contact resistance through said metal surface of less than or equal to about 0.3 ohm-cm^2.

24. The method of claim 23 wherein the epoxy has an effective metal surface wetting concentration of silane to form a cured electrical interconnection having a resistance through said metal surface of less than or equal to about 0.16 ohm- cm^2.

25. The method of claim 23 wherein the epoxy has an effective metal surface wetting concentration of silane to form a cured electrical interconnection having a resistance through said metal surface of less than or equal to about 0.032 ohm- cm^2.

26. The method of claim 23 wherein the metal surface wetting concentration of silane in the curable adhesive composition is less than or equal to about 2% by weight.

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27. The method of claim 23 wherein the metal surface wetting concentration of silane in the curable adhesive composition is less than or equal to about 1% by weight.

28. The method of claim 23 wherein the metal surface comprises nickel over which the curable adhesive composition is received.

Cancel claims 29-50 without prejudice.